

ABSTRACT OF THE DISCLOSURE

An IC chip package is constructed to include a substrate, a chip, adhesive
5 means, a cover, and a spacer. The substrate has a top side, a bottom side, and a
plurality of conductive pads at the top side. The chip is fixedly mounted in the
top side of the substrate, having a plurality of conductive pads respectively
electrically connected to the conductive pads of substrate by respective bonding
wires. The adhesive means is provided at the top side of the substrate around the
10 border area. The spacer is connected between the substrate and the cover to
keep the cover from the substrate at a distance. The spacer has at least two
columns fixedly connected between the substrate and the cover.